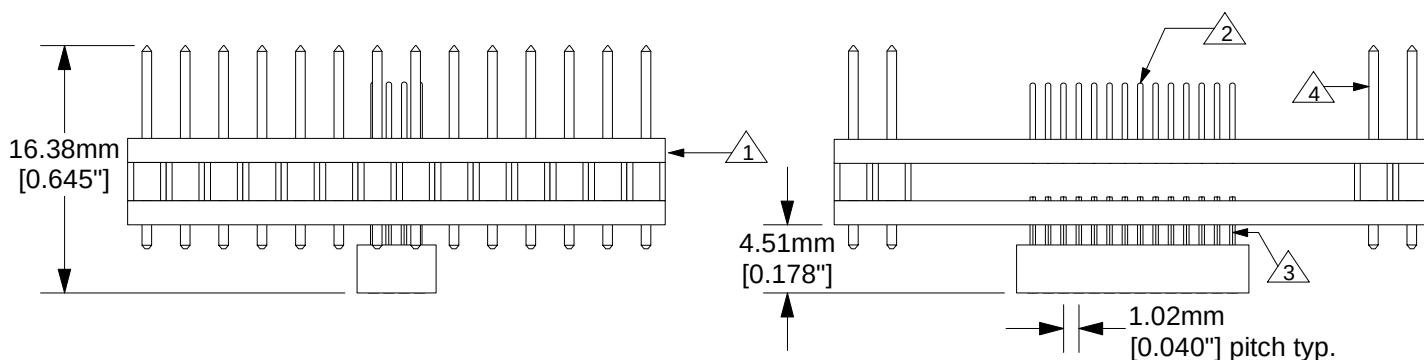
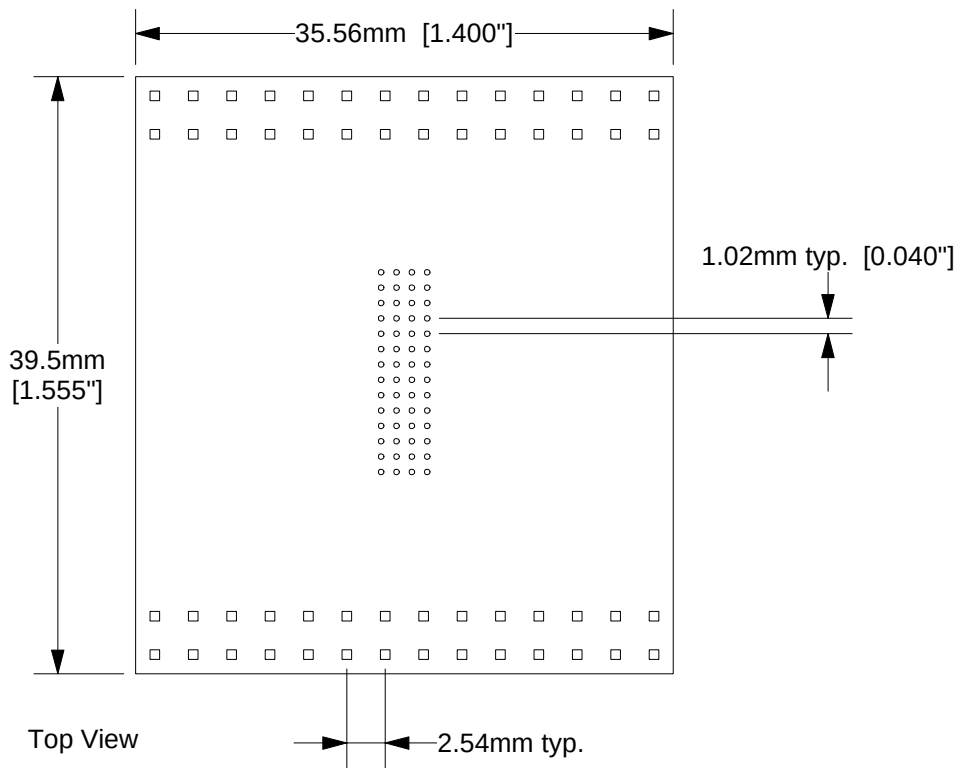




- 1 Substrate: 1.59mm $\pm$ 0.18mm [0.0625" $\pm$ 0.007"] FR4/G10 or equivalent high temp material. 17 μ m [1/2 oz.] Cu clad. SnPb plating.
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ "] Au over 1.27 μ m [50 μ "] Ni (min.).

- 3 Pins: shell material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ "] Au over 1.27 μ m [50 μ "] Ni (min.). Contact material- BeCu; finish 0.25 μ m [10 μ "] Au over 2.54 μ m [100 μ "] Ni (min.).
- 4 Test points: material- Phosphor Bronze; plating- Sn over 1.27 μ m [50 μ "] Ni. Gold flash on contact end.

Description: Probe board (PB), TSOP

56 position male mini grid array (MGA) pins with test points to female MGA pins.

Tolerances: diameters $\pm$ 0.03mm [$\pm$ 0.001"], PCB perimeters $\pm$ 0.13mm [$\pm$ 0.005"], PCB thicknesses $\pm$ 0.18mm [$\pm$ 0.007"], pitches (from true position) $\pm$ 0.08mm [$\pm$ 0.003"], all other tolerances $\pm$ 0.13mm [$\pm$ 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

PB-SO56-01 Drawing	Status: Released	Scale: 2:1	Rev: D
 © 1999 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: E Smolentseva	Date: 6/16/99	
	File: PB-SO56-01 Dwg.mcd	Modified: 8/16/01, ELS	